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1-800-375-0605
www.rudolphbros.com

TECHNICAL BULLETIN

EPOXIBOND-107-FC **HIGH IMPACT, LOW VISCOSITY EPOXY ADHESIVE**

EB-107-FC is a two component, room temperature curing epoxy featuring very low viscosity, and excellent optical-mechanical properties.

Features & Suggested Application:

- Semiconductor: optical glob top or underfill; compatible with LED die, Si, GaAs
- PCB: general potting and protection over FR4, flex, or ceramic PCBs
- **Medical:** Meets USP Class VI Biocompatibility standards - Suggested for medical devices such as catheters, endoscopic products; adhesion to most metals and some plastics; resisting to ETO, gamma, and autoclave; resisting X-ray radiation; potting and protection of scintillator crystals; CT Detector packaging; adhesive for the optical beam pathway in photo-diode arrays.
- **Fiber Optic:** adhesive for glass and plastic fibers; wicking into fiber bundles used in patch cords, endoscopes or sensor devices; adhesive/seal/encapsulant used for fiber packaging and components
- **Opto-electronic:** LCD/LED adhesive for laminating glass layers; adhesion to PET plastic; general potting, encapsulation, and protection; spectral transmission in VIS and IR light; adhesive for precision optics including lens, prism, beam splitter cubes, mirrors, and diodes

TYPICAL HANDLING PROPERTIES:

Adhesive	PART-A
Hardener	PART-B
Mix ratio by weight, (Adhesive/Hardener)	100/25
Mixed Viscosity at 25°C, cp	100-200
Pot Life at 25°C (100 grams), min	20-25
Recommended Cure	3 hr at 65°C
Alternate Cure Schedule	24-48 hr at 25°C

TYPICAL CURED PROPERTIES:

(Tested @ 25°C unless otherwise indicated)

Color	Clear
Specific Gravity	1.1
Hardness, Shore D	82
Lap Shear Strength to Aluminum, psi	2400
Service Temperature range, °C	-55 to 200
Refractive Index	1.52
Glass Transition Temperature, °C	65
Coefficient of Linear Thermal Expansion, 10 ⁻⁶ /°C	
Below Tg	42
Above Tg	>100
Dielectric Constant at 1 kHz	4.14
Dissipation Factor at 1 kHz	0.012
Volume Resistivity (ohm-cm)	1x10 ¹³

INSTRUCTIONS FOR USE:

1. Mix 100 grams of Resin, PART-A with 25 grams of Hardener, PART-B and vacuum degas.
2. Apply to clean bonding surfaces and cure as recommended to achieve the desired properties.
3. Typical cured properties were determined using recommended cure schedule.
4. Some difference in properties may occur with the alternate or other cure schedules.

FOR INDUSTRIAL USE ONLY:

These materials are intended for industrial use only, and the practices of good housekeeping, safety and cleanliness should be followed before, during and after use.

WARNING!

Although the system contains low volatility materials, care should be taken in handling. Adequate ventilation of work place and ovens is essential. These materials may cause injury to the skin following prolonged or repeated contact and dermatitis in susceptible individuals. In case of skin contact, wash thoroughly with soap and water. For eyes, flush immediately with plenty of water for at least 10 minutes and seek medical attention. Refer to Material Safety Data Sheet for additional health and safety information.

SHELF LIFE:

The shelf life of these materials is greater than one year when stored in unopened containers at an average temperature of 25°C.

DISCLAIMER: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performance. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not to be construed as recommendations to infringe any patent.